
HM51W17800 Series

2,097,152-word × 8-bit Dynamic RAM

HITACHI

ADE-203-664C (Z)

Rev. 3.0

Feb. 24, 1997

Description

The Hitachi HM51W17800 is a CMOS dynamic RAM organized 2,097,152-word × 8-bit. It employs the most advanced CMOS technology for high performance and low power. The HM51W17800 offers Fast Page Mode as a high speed access mode. Multiplexed address input permits the HM51W17800 to be packaged in standard 28-pin plastic SOJ and 28-pin TSOP.

Features

- Single 3.3 V (± 0.3 V)
- Access time: 50 ns/60 ns/70 ns (max)
- Power dissipation
 - Active mode: 396 mW/360 mW/324 mW (max)
 - Standby mode
 - 7.2 mW (max)
 - 0.54 mW (max) (L-version)
- Fast page mode capability
- Refresh cycles
 - 2048 refresh cycles
 - 32 ms
 - 128 ms (L-version)
- 4 variations of refresh
 - $\overline{\text{RAS}}$ -only refresh
 - $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh
 - Hidden refresh
 - Self refresh (L-version)
- Battery backup operation (L-version)

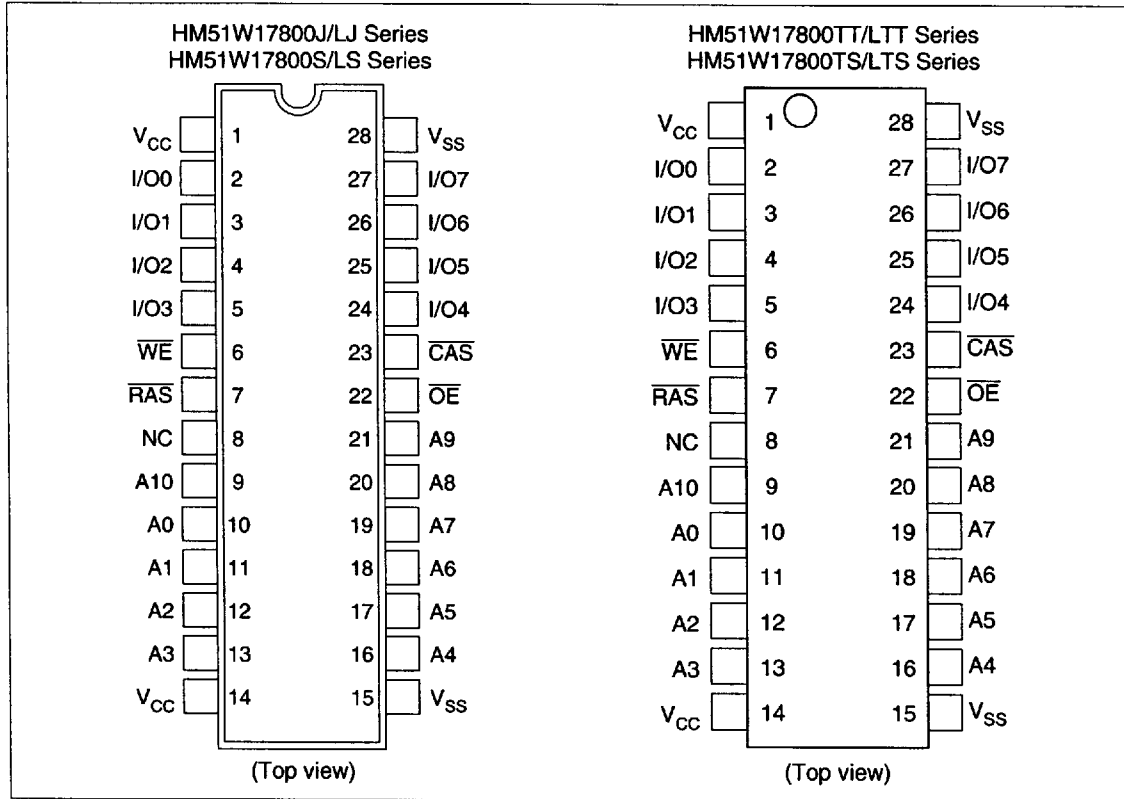
HM51W17800 Series

Ordering Information

Type No.	Access time	Package
HM51W17800J-5	50 ns	400-mil 28-pin plastic SOJ (CP-28DA)
HM51W17800J-6	60 ns	
HM51W17800J-7	70 ns	
HM51W17800LJ-5	50 ns	400-mil 28-pin plastic SOJ (CP-28DA)
HM51W17800LJ -6	60 ns	
HM51W17800LJ -7	70 ns	
HM51W17800S-5	50 ns	300-mil 28-pin plastic SOJ (CP-28DNA)
HM51W17800S-6	60 ns	
HM51W17800S-7	70 ns	
HM51W17800LS-5	50 ns	300-mil 28-pin plastic SOJ (CP-28DNA)
HM51W17800LS-6	60 ns	
HM51W17800LS-7	70 ns	
HM51W17800TT-5	50 ns	400-mil 28-pin plastic TSOP II (TTP-28DA)
HM51W17800TT-6	60 ns	
HM51W17800TT-7	70 ns	
HM51W17800LTT-5	50 ns	400-mil 28-pin plastic TSOP II (TTP-28DA)
HM51W17800LTT-6	60 ns	
HM51W17800LTT-7	70 ns	
HM51W17800TS-5	50 ns	300-mil 28-pin plastic TSOP II (TTP-28DB)
HM51W17800TS-6	60 ns	
HM51W17800TS-7	70 ns	
HM51W17800LTS-5	50 ns	300-mil 28-pin plastic TSOP II (TTP-28DB)
HM51W17800LTS-6	60 ns	
HM51W17800LTS-7	70 ns	

HM51W17800 Series

Pin Arrangement

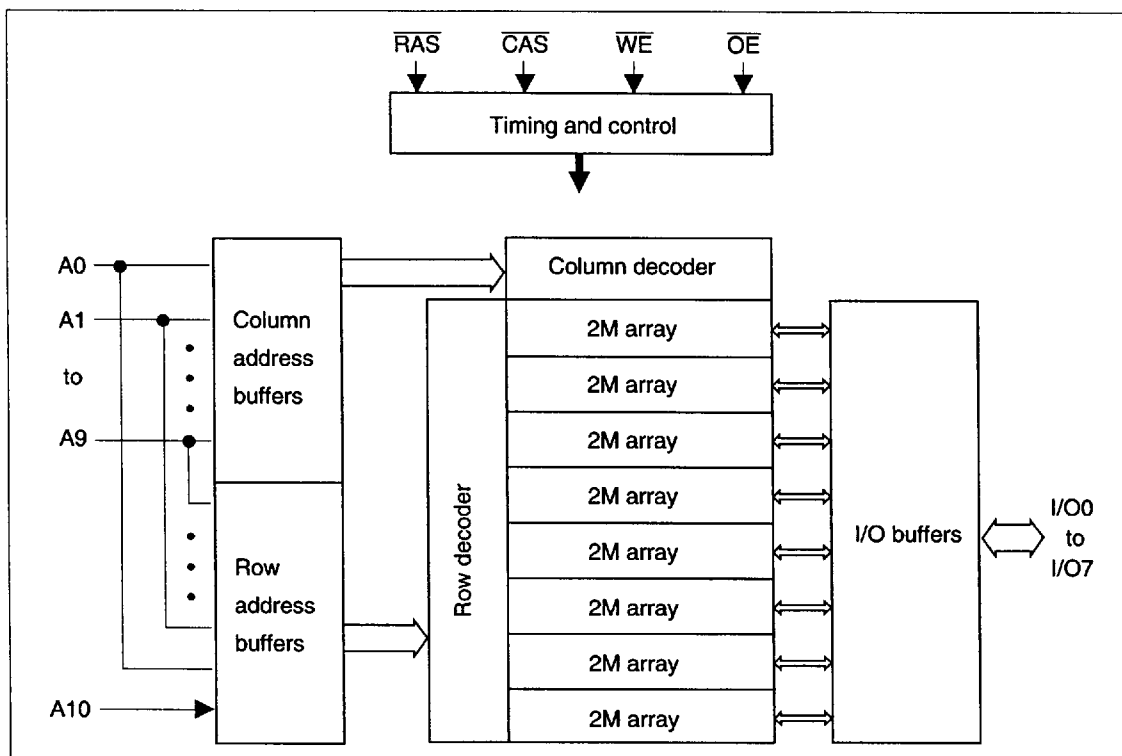


Pin Description

Pin name	Function
A0 to A10	Address input Row/Refresh address A0 to A10 Column address A0 to A9
I/O0 to I/O7	Data input/data output
RAS	Row address strobe
CAS	Column address strobe
WE	Read/Write enable
OE	Output enable
V _{CC}	Power supply
V _{SS}	Ground
NC	No connection

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Block Diagram



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	-0.5 to +4.6	V
Supply voltage relative to V_{SS}	V_{CC}	-0.5 to +4.6	V
Short circuit output current	I_{out}	50	mA
Power dissipation	P_T	1.0	W
Operating temperature	T_{opr}	0 to +70	°C
Storage temperature	T_{stg}	-55 to +125	°C

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Recommended DC Operating Conditions (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Supply voltage	V _{CC}	3.0	3.3	3.6	V	1, 2
Input high voltage	V _{IH}	2.0	—	V _{CC} + 0.3	V	1
Input low voltage	V _{IL}	−0.3	—	0.8	V	1

Notes: 1. All voltage referred to V_{SS}

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DC Characteristics ($T_a = 0$ to $+70^\circ\text{C}$, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$, $V_{SS} = 0\text{ V}$)

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test conditions
Operating current*1, *2	I _{CC1}	—	110	—	100	—	90	mA	t _{RC} = min
Standby current	I _{CC2}	—	2	—	2	—	2	mA	TTL interface RAS, CAS = V _{IH} Dout = High-Z
Standby current		—	1	—	1	—	1	mA	CMOS interface RAS, CAS ≥ V _{CC} − 0.2V Dout = High-Z
Standby current (L-version)	I _{CC2}	—	150	—	150	—	150	μA	CMOS interface RAS, CAS ≥ V _{CC} − 0.2V Dout = High-Z
RAS-only refresh current*2	I _{CC3}	—	110	—	100	—	90	mA	t _{RC} = min
Standby current*1	I _{CC5}	—	5	—	5	—	5	mA	RAS = V _{IH} CAS = V _{IL} Dout = enable
CAS-before-RAS refresh current	I _{CC6}	—	110	—	100	—	90	mA	t _{RC} = min
Fast page mode current*1, *3	I _{CC7}	—	100	—	90	—	85	mA	t _{PC} = min
Battery backup current*4 (Standby with CBR refresh) (L-version)	I _{CC10}	—	400	—	400	—	400	μA	CMOS interface Dout = High-Z CBR refresh: t _{RC} = 62.5 μs t _{RAS} ≤ 0.3 μs
Self refresh mode current (L-version)	I _{CC11}	—	250	—	250	—	250	μA	CMOS interface RAS, CAS ≤ 0.2V Dout = High-Z
Input leakage current	I _{LI}	−10	10	−10	10	−10	10	μA	0 V ≤ Vin ≤ 4.6 V
Output leakage current	I _{LO}	−10	10	−10	10	−10	10	μA	0 V ≤ Vout ≤ 4.6 V Dout = disable
Output high voltage	V _{OH}	2.4	V _{CC}	2.4	V _{CC}	2.4	V _{CC}	V	High Iout = −2 mA
Output low voltage	V _{OL}	0	0.4	0	0.4	0	0.4	V	Low Iout = 2 mA

Notes: 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.

2. Address can be changed once or less while $\overline{\text{RAS}} = V_{IL}$.

3. Address can be changed once or less while $\overline{\text{CAS}} = V_{IH}$.

4. $\overline{\text{CAS}} = L (\leq 0.2\text{ V})$ while $\overline{\text{RAS}} = L (\leq 0.2\text{ V})$.

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Capacitance ($T_a = 25^\circ\text{C}$, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C_{I1}	—	5	pF	1
Input capacitance (Clocks)	C_{I2}	—	7	pF	1
Output capacitance (Data-in, Data-out)	C_{IO}	—	7	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
2. $\overline{\text{CAS}} = V_{IH}$ to disable Dout.

AC Characteristics ($T_a = 0$ to $+70^\circ\text{C}$, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$, $V_{SS} = 0\text{ V}$)*1, *2, *18**Test Conditions**

- Input rise and fall time: 5 ns
- Input timing reference levels: 0.8 V, 2.0 V
- Output timing reference levels: 0.8 V, 2.0 V
- Output load: 1 TTL gate + C_L (100 pF) (Including scope and jig)

HM51W17800 Series

Read, Write, Read-Modify-Write and Refresh Cycles (Common parameters)

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t_{RC}	90	—	110	—	130	—	ns	
$\overline{RAS}$ precharge time	t_{RP}	30	—	40	—	50	—	ns	
$\overline{CAS}$ precharge time	t_{CP}	8	—	10	—	10	—	ns	
$\overline{RAS}$ pulse width	t_{RAS}	50	10000	60	10000	70	10000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	13	10000	15	10000	18	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	0	—	ns	
Row address hold time	t_{RAH}	8	—	10	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	0	—	ns	
Column address hold time	t_{CAH}	8	—	10	—	15	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	18	37	20	45	20	52	ns	3
$\overline{RAS}$ to column address delay time	t_{RAD}	13	25	15	30	15	35	ns	4
$\overline{RAS}$ hold time	t_{RSH}	13	—	15	—	18	—	ns	
$\overline{CAS}$ hold time	t_{CSH}	50	—	60	—	70	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	5	—	5	—	5	—	ns	
$\overline{OE}$ to Din delay time	t_{OED}	13	—	15	—	18	—	ns	5
$\overline{OE}$ delay time from Din	t_{DZO}	0	—	0	—	0	—	ns	6
$\overline{CAS}$ delay time from Din	t_{DZC}	0	—	0	—	0	—	ns	6
Transition time (rise and fall)	t_T	3	50	3	50	3	50	ns	7

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Read Cycle

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Access time from $\overline{\text{RAS}}$	t_{RAC}	—	50	—	60	—	70	ns	8, 9
Access time from $\overline{\text{CAS}}$	t_{CAC}	—	13	—	15	—	18	ns	9, 10, 17,
Access time from address	t_{AA}	—	25	—	30	—	35	ns	9, 11, 17,
Access time from $\overline{\text{OE}}$	t_{OEA}	—	13	—	15	—	18	ns	9
Read command setup time	t_{RCS}	0	—	0	—	0	—	ns	
Read command hold time to $\overline{\text{CAS}}$	t_{RCH}	0	—	0	—	0	—	ns	12
Read command hold time to $\overline{\text{RAS}}$	t_{RRH}	0	—	0	—	0	—	ns	12
Column address to $\overline{\text{RAS}}$ lead time	t_{RAL}	25	—	30	—	35	—	ns	
Column address to $\overline{\text{CAS}}$ lead time	t_{CAL}	25	—	30	—	35	—	ns	
$\overline{\text{CAS}}$ to output in low-Z	t_{CLZ}	0	—	0	—	0	—	ns	
Output data hold time	t_{OH}	3	—	3	—	3	—	ns	
Output data hold time from $\overline{\text{OE}}$	t_{OHO}	3	—	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	13	—	15	—	15	ns	13
Output buffer turn-off to $\overline{\text{OE}}$	t_{OEZ}	—	13	—	15	—	15	ns	13
$\overline{\text{CAS}}$ to Din delay time	t_{CDD}	13	—	15	—	18	—	ns	5

Write Cycle

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write command setup time	t_{WCS}	0	—	0	—	0	—	ns	14
Write command hold time	t_{WCH}	8	—	10	—	15	—	ns	
Write command pulse width	t_{WP}	8	—	10	—	10	—	ns	
Write command to $\overline{\text{RAS}}$ lead time	t_{RWL}	13	—	15	—	18	—	ns	
Write command to $\overline{\text{CAS}}$ lead time	t_{CWL}	13	—	15	—	18	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	0	—	ns	15
Data-in hold time	t_{DH}	8	—	10	—	15	—	ns	15

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Read-Modify-Write Cycle

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read-modify-write cycle time	t_{RWC}	131	—	155	—	181	—	ns	
RAS to $\overline{WE}$ delay time	t_{RWD}	73	—	85	—	98	—	ns	14
CAS to $\overline{WE}$ delay time	t_{CWD}	36	—	40	—	46	—	ns	14
Column address to $\overline{WE}$ delay time	t_{AWD}	48	—	55	—	63	—	ns	14
$\overline{OE}$ hold time from $\overline{WE}$	t_{OEh}	13	—	15	—	18	—	ns	

Refresh Cycle

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
CAS setup time (CBR refresh cycle)	t_{CSR}	5	—	5	—	5	—	ns	
CAS hold time (CBR refresh cycle)	t_{CHR}	8	—	10	—	10	—	ns	
$\overline{WE}$ setup time (CBR refresh cycle)	t_{WRP}	0	—	0	—	0	—	ns	
$\overline{WE}$ hold time (CBR refresh cycle)	t_{WRH}	8	—	10	—	10	—	ns	
RAS precharge to CAS hold time	t_{RPC}	5	—	5	—	5	—	ns	

Fast Page Mode Cycle

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Fast page mode cycle time	t_{PC}	35	—	40	—	45	—	ns	
Fast page mode RAS pulse width	t_{RASP}	—	100000	—	100000	—	100000	ns	16
Access time from CAS precharge	t_{CPA}	—	30	—	35	—	40	ns	9, 17
RAS hold time from CAS precharge	t_{CPRH}	30	—	35	—	40	—	ns	

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Fast Page Mode Read-Modify-Write Cycle

		HM51W17800							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Fast page mode read-modify-write cycle time	t _{PRWC}	76	—	85	—	96	—	ns	
WE delay time from $\overline{\text{CAS}}$ precharge	t _{CPW}	53	—	60	—	68	—	ns	14

Refresh

Parameter	Symbol	Max	Unit	Note
Refresh period	t_{REF}	32	ms	2048 cycles
Refresh period (L-version)	t_{REF}	128	ms	2048 cycles

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Self Refresh Mode (L-version)

		HM51W17800L							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
$\overline{\text{RAS}}$ pulse width (self refresh)	t_{RASS}	100	—	100	—	100	—	μs	19, 20, 21, 22
$\overline{\text{RAS}}$ precharge time (self refresh)	t_{RPS}	90	—	110	—	130	—	ns	
$\overline{\text{CAS}}$ hold time (self refresh)	t_{CHS}	-50	—	-50	—	-50	—	ns	

- Notes: 1. AC measurements assume $t_f = 5$ ns.
- An initial pause of 200 μs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{\text{RAS}}$ -only refresh or $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh). If the internal refresh counter is used, a minimum of eight $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycles are required.
 - Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC} .
 - Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA} .
 - Either t_{OED} or t_{CDD} must be satisfied.
 - Either t_{DZO} or t_{DZC} must be satisfied.
 - V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
 - Assumes that $t_{\text{RCD}} \leq t_{\text{RCD}}$ (max) and $t_{\text{RAD}} \leq t_{\text{RAD}}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
 - Measured with a load circuit equivalent to 1 TTL loads and 100 pF. ($V_{\text{OH}} = 2.0$ V, $V_{\text{OL}} = 0.8$ V)
 - Assumes that $t_{\text{RCD}} \geq t_{\text{RCD}}$ (max) and $t_{\text{RAD}} \leq t_{\text{RAD}}$ (max).
 - Assumes that $t_{\text{RCD}} \leq t_{\text{RCD}}$ (max) and $t_{\text{RAD}} \geq t_{\text{RAD}}$ (max).
 - Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
 - t_{OFF} (max) and t_{OEZ} (max) define the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
 - t_{WCS} , t_{RWD} , t_{CWD} , t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{\text{WCS}} \geq t_{\text{WCS}}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{\text{RWD}} \geq t_{\text{RWD}}$ (min), $t_{\text{CWD}} \geq t_{\text{CWD}}$ (min), and $t_{\text{AWD}} \geq t_{\text{AWD}}$ (min), or $t_{\text{CWD}} \geq t_{\text{CWD}}$ (min), $t_{\text{AWD}} \geq t_{\text{AWD}}$ (min) and $t_{\text{CPW}} \geq t_{\text{CPW}}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
 - These parameters are referred to $\overline{\text{CAS}}$ leading edge in early write cycles and to $\overline{\text{WE}}$ leading edge in delayed write or read-modify-write cycles.
 - t_{RASp} defines $\overline{\text{RAS}}$ pulse width in Fast page mode cycles.
 - Access time is determined by the longest among t_{AA} , t_{CAC} and t_{CPA} .
 - In delayed write or read-modify-write cycles, $\overline{\text{OE}}$ must disable output buffer prior to applying data to the device.
 - Please do not use t_{RASS} timing, $10 \mu\text{s} \leq t_{\text{RASS}} \leq 100 \mu\text{s}$. During this period, the device is in transition state from normal operation mode to self refresh mode. If $t_{\text{RASS}} \geq 100 \mu\text{s}$, then $\overline{\text{RAS}}$ precharge time should use t_{RPS} instead of t_{RP} .

20. If you use $\overline{\text{RAS}}$ only refresh or CBR burst refresh mode in normal read/write cycles, 2048 cycles of distributed CBR refresh with 15.6 μs interval should be executed within 32 ms immediately after exiting from and before entering into the self refresh mode.
21. If you use distributed CBR refresh mode with 15.6 μs interval in normal read/write cycle, CBR refresh should be executed within 15.6 μs immediately after exiting from and before entering into self refresh mode.
22. Repetitive self refresh mode without refreshing all memory is not allowed. Once you exit from self refresh mode, all memory cells need to be refreshed before re-entering the self refresh mode again.
23. XXX: H or L (H: $V_{\text{IH}}(\text{min}) \leq V_{\text{IN}} \leq V_{\text{IH}}(\text{max})$, L: $V_{\text{IL}}(\text{min}) \leq V_{\text{IN}} \leq V_{\text{IL}}(\text{max})$)
/////: Invalid Dout
When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL} .

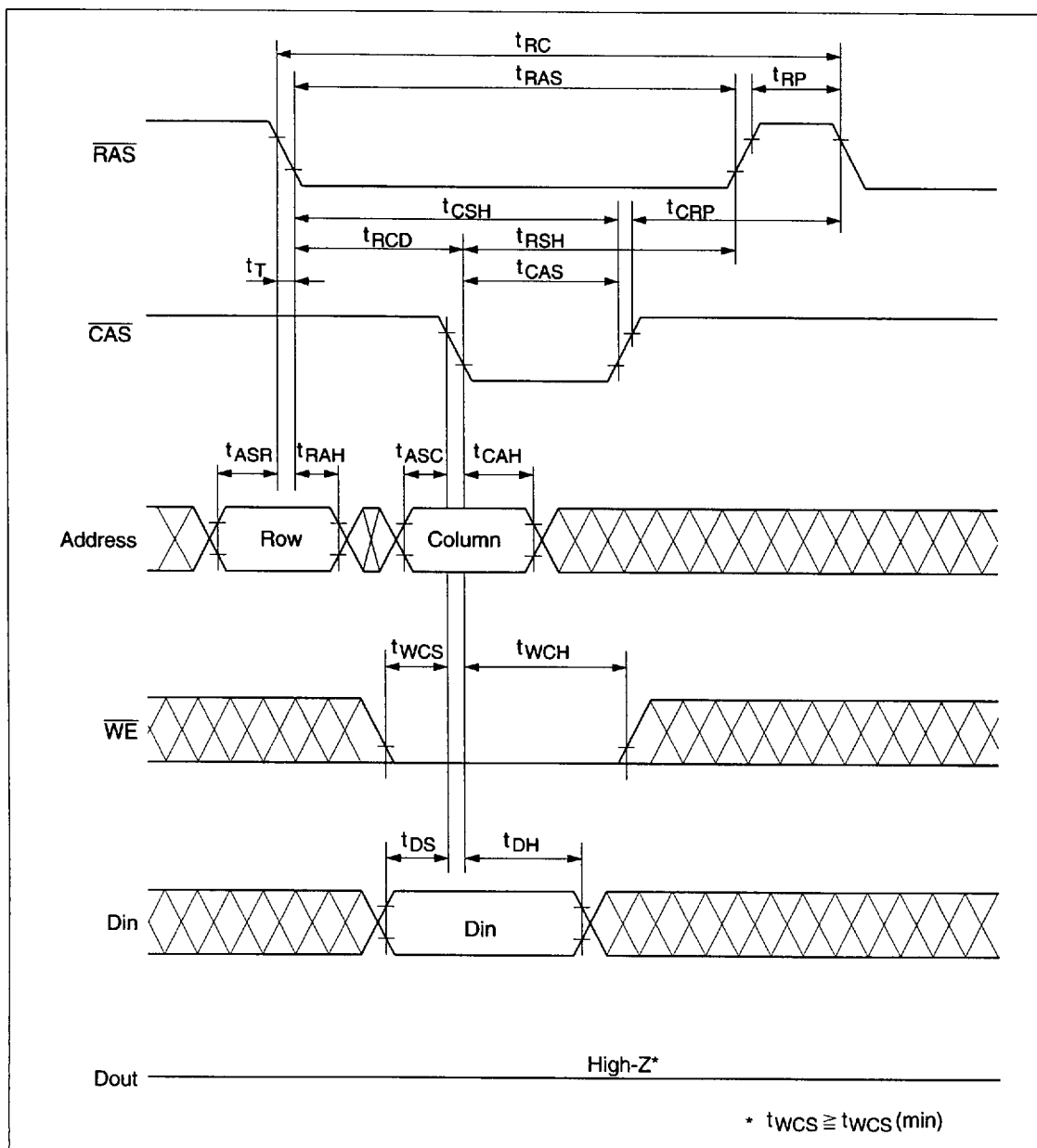
HM51W17800 Series

Timing Waveforms*23

Read Cycle

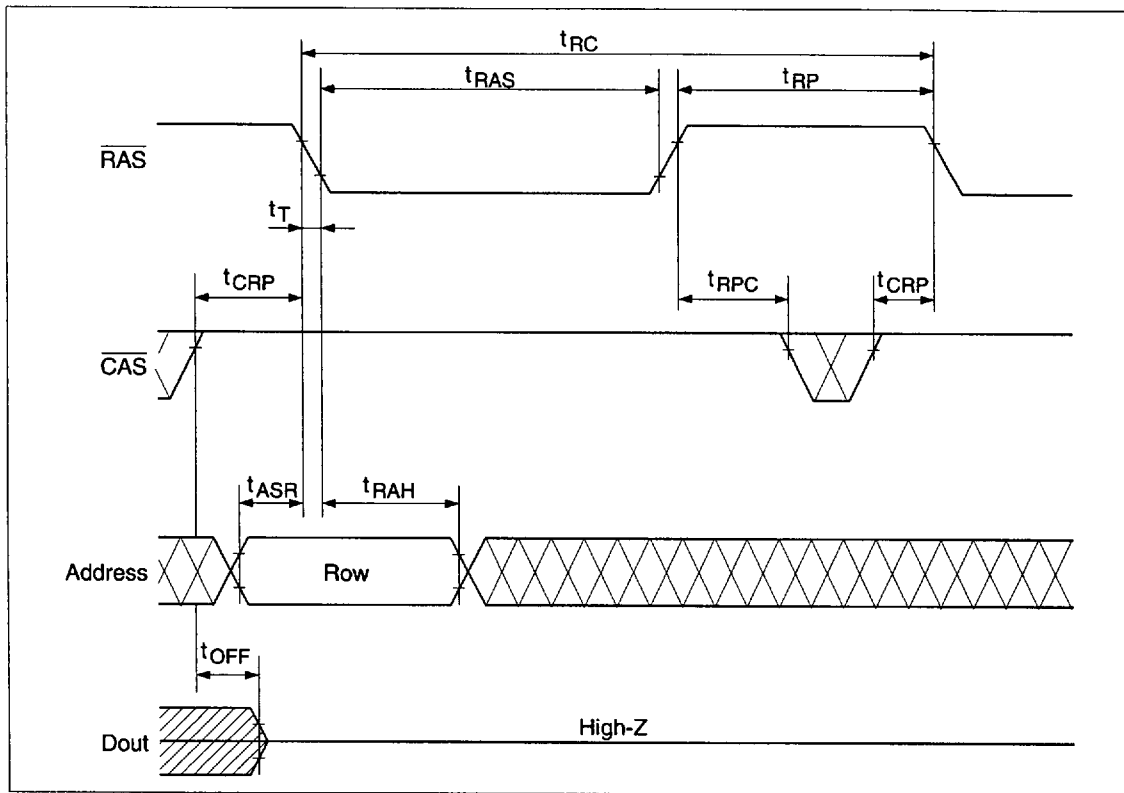
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HM51W17800 Series



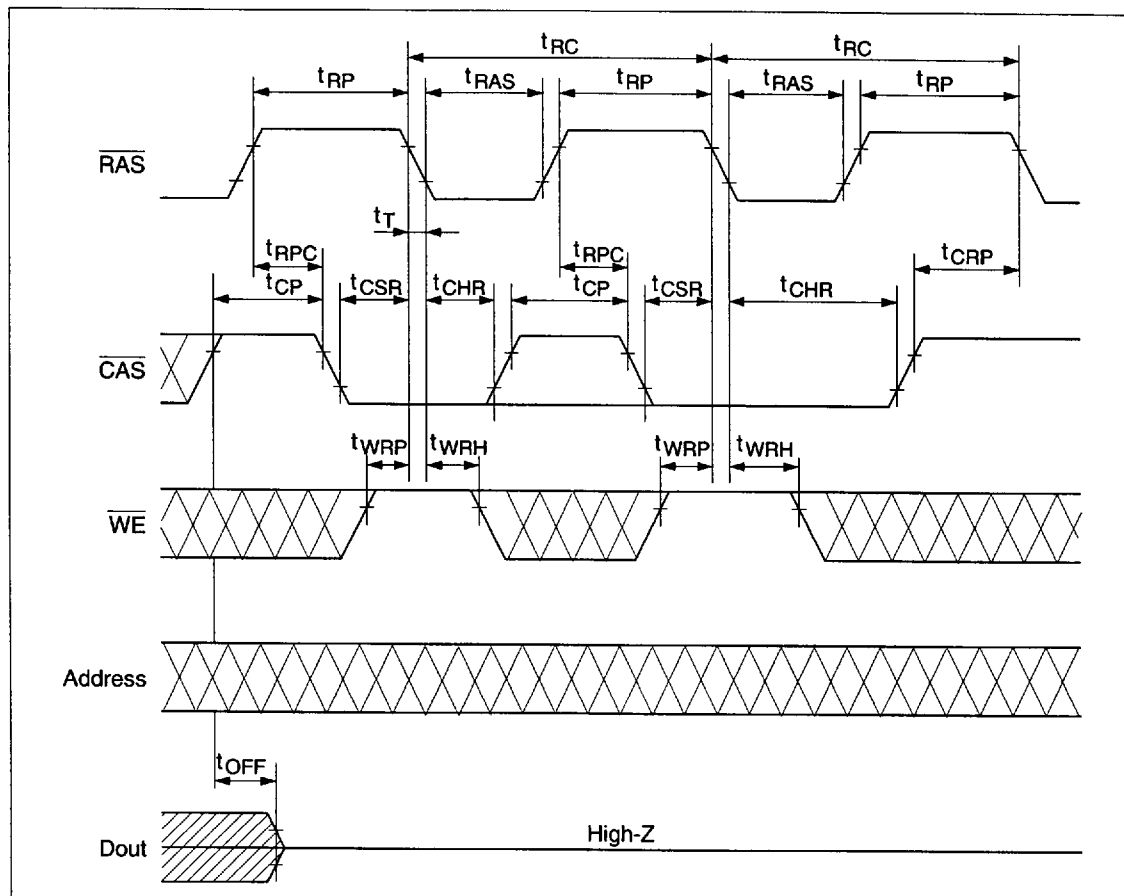


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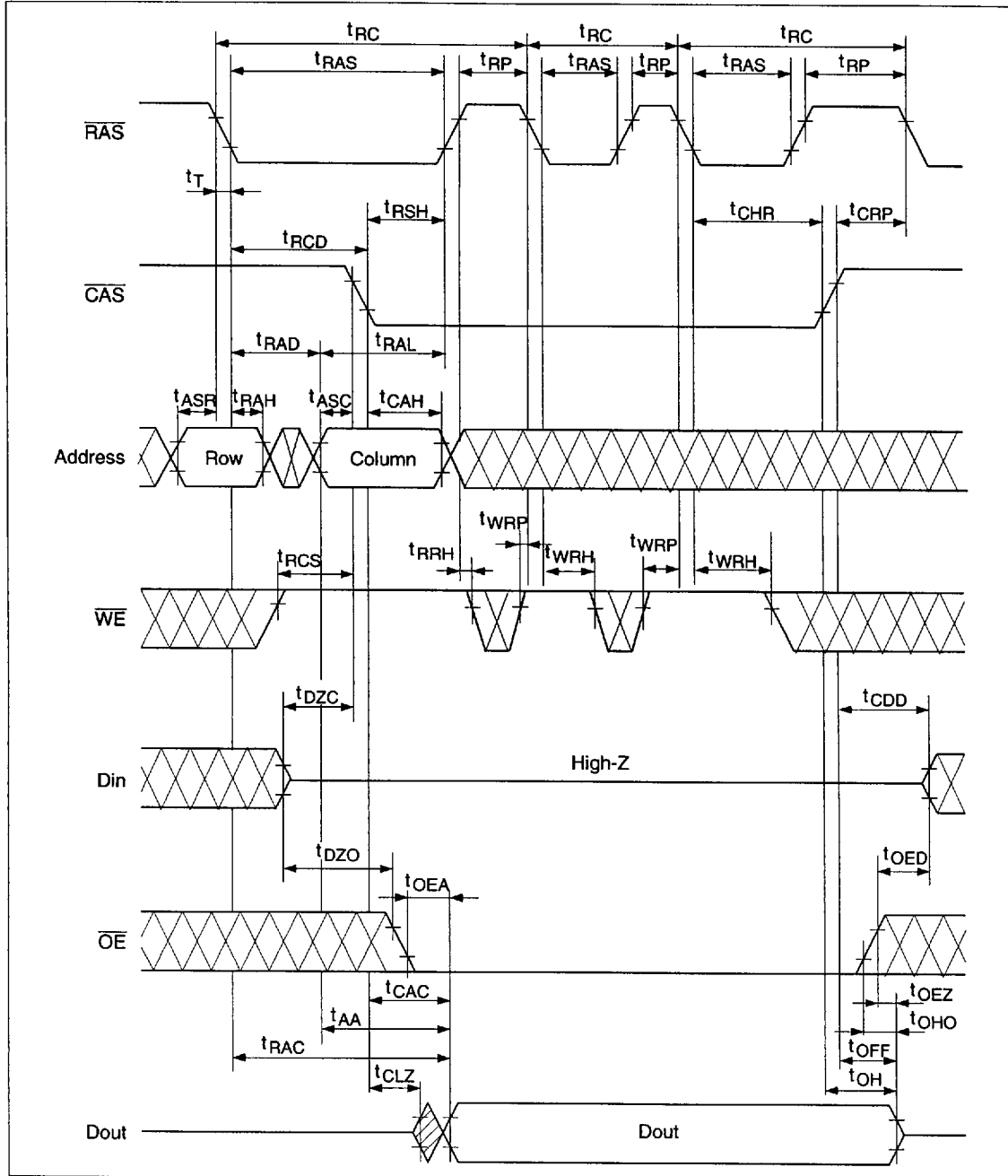


HM51W17800 Series

CAS-Before-RAS Refresh Cycle



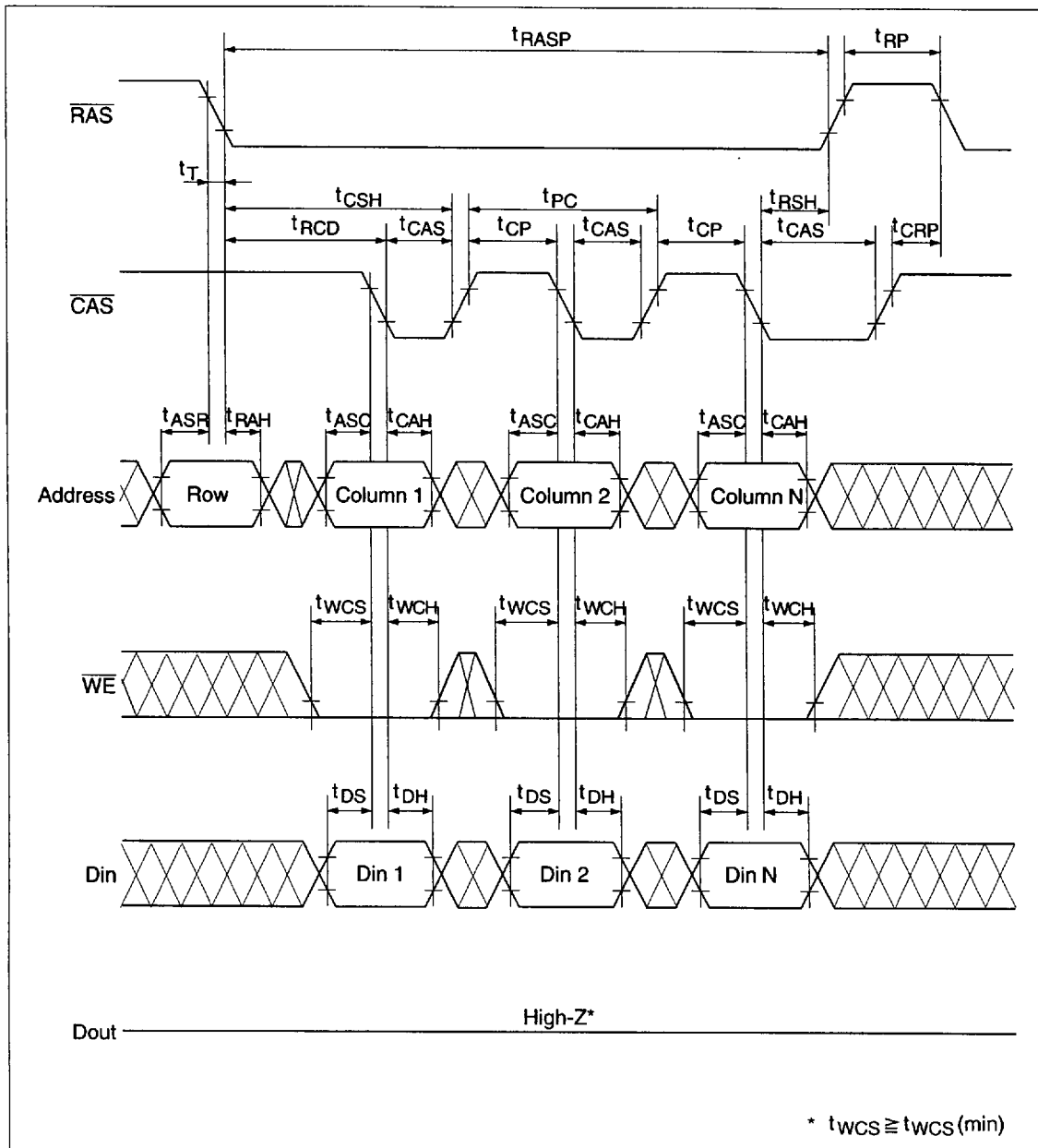
Hidden Refresh Cycle



Fast Page Mode Read Cycle

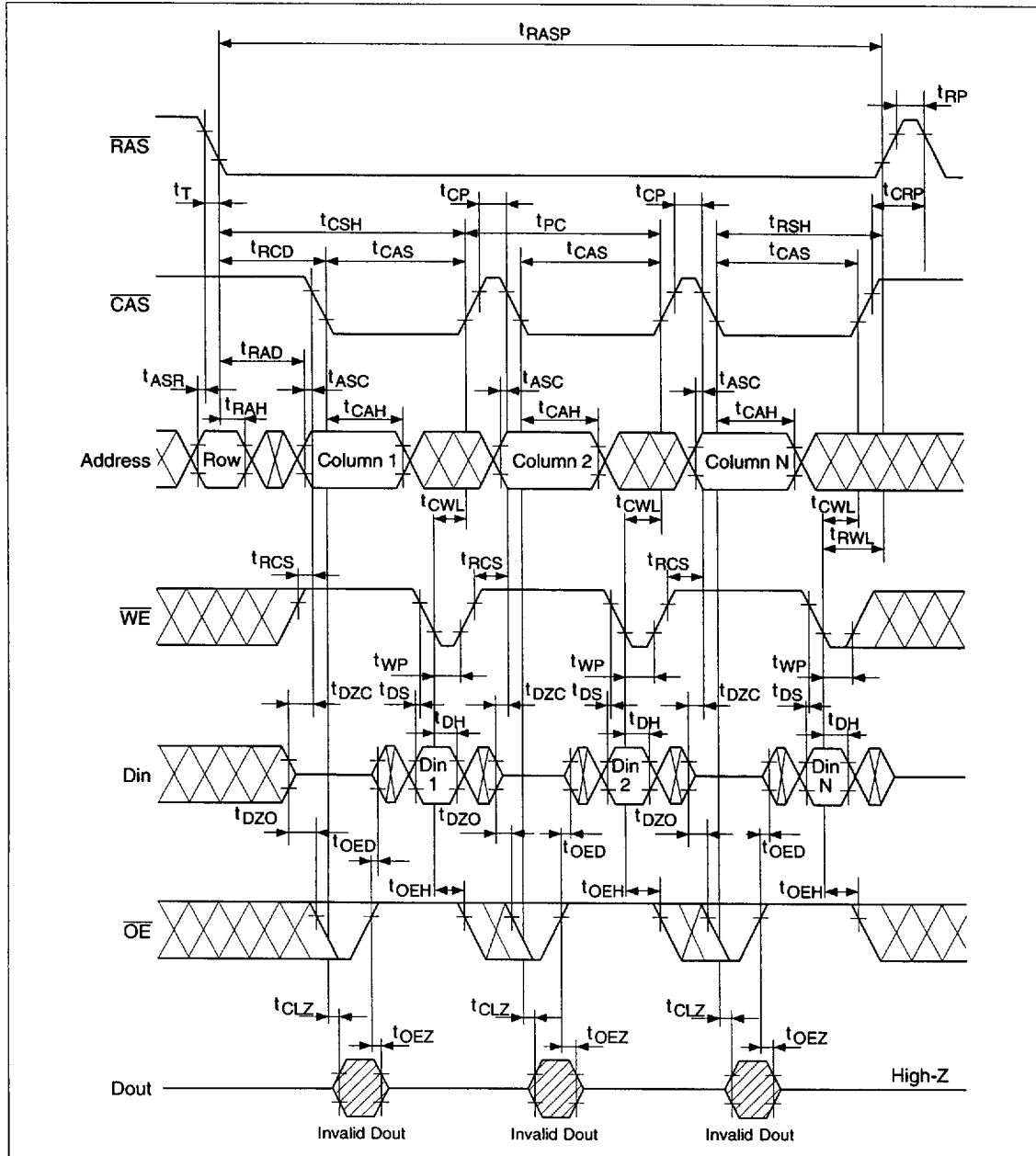
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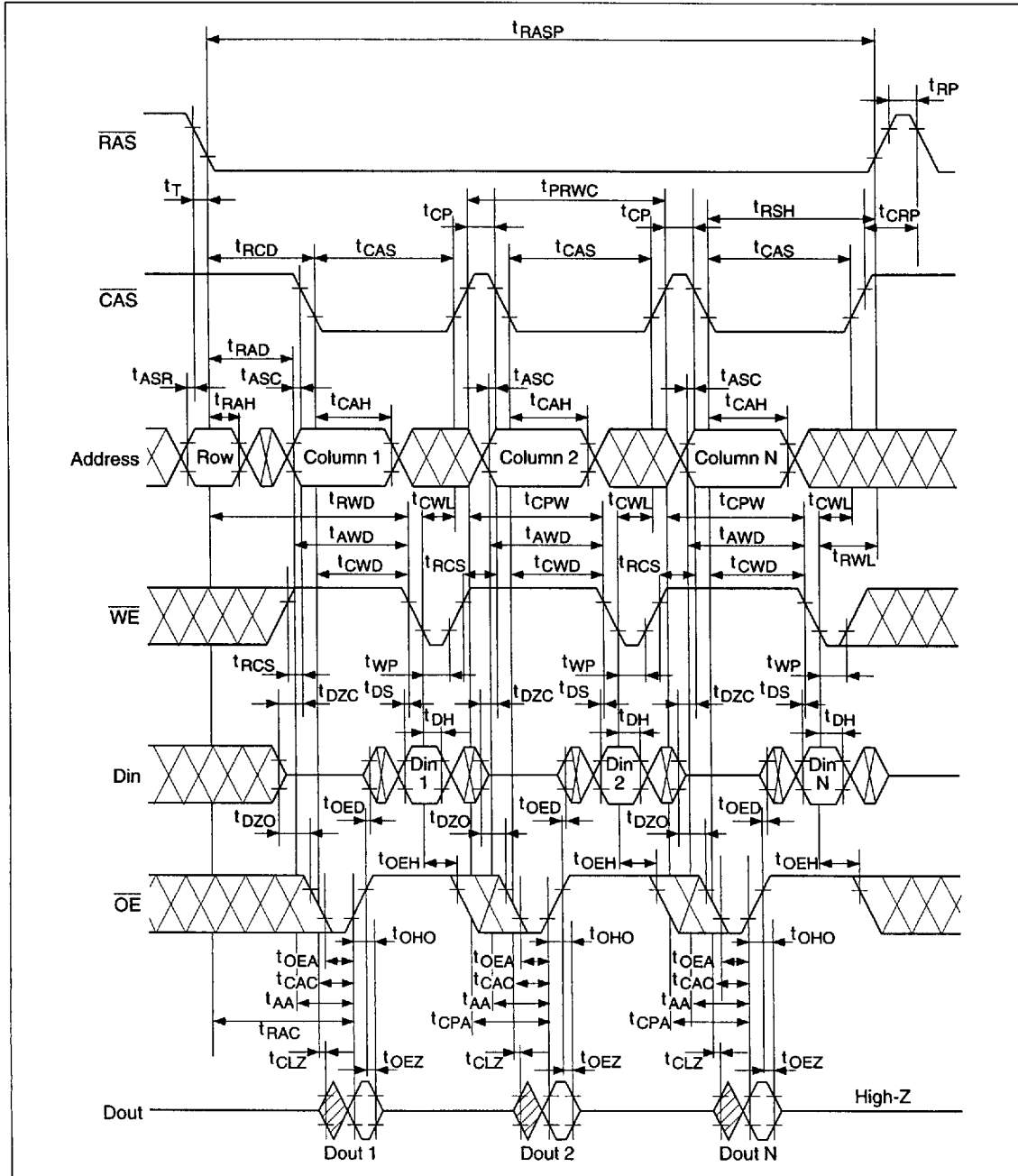


HM51W17800 Series

Fast Page Mode Delayed Write Cycle*18

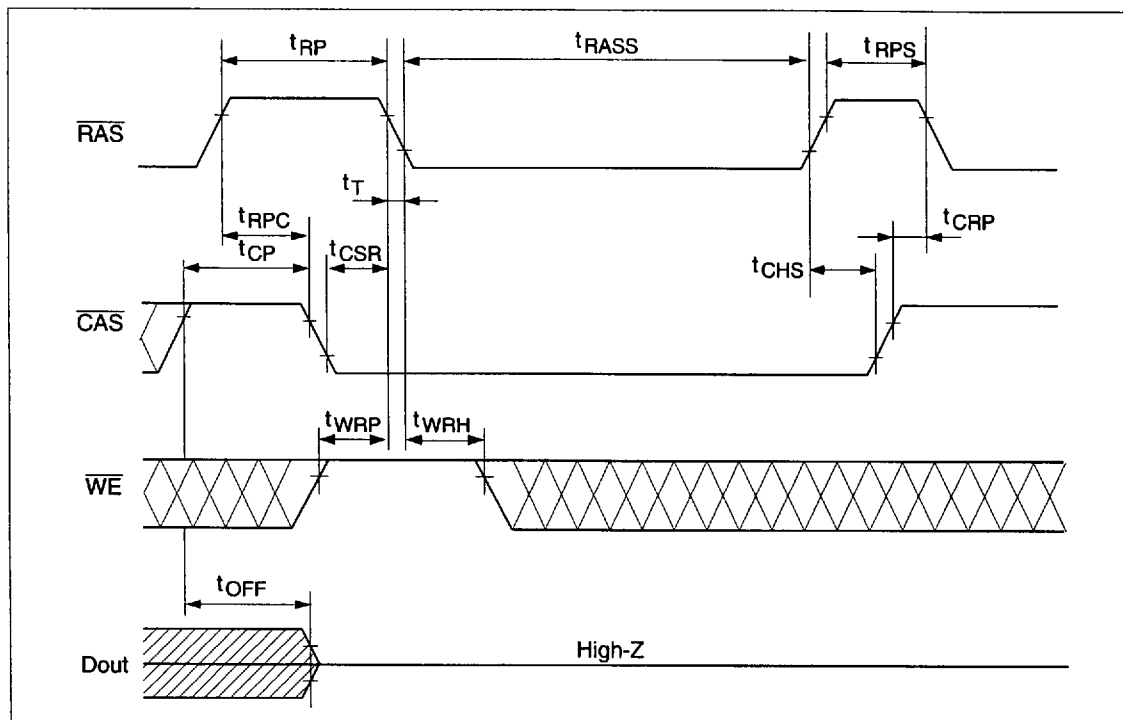


Fast Page Mode Read-Modify-Write Cycle*18



HM51W17800 Series

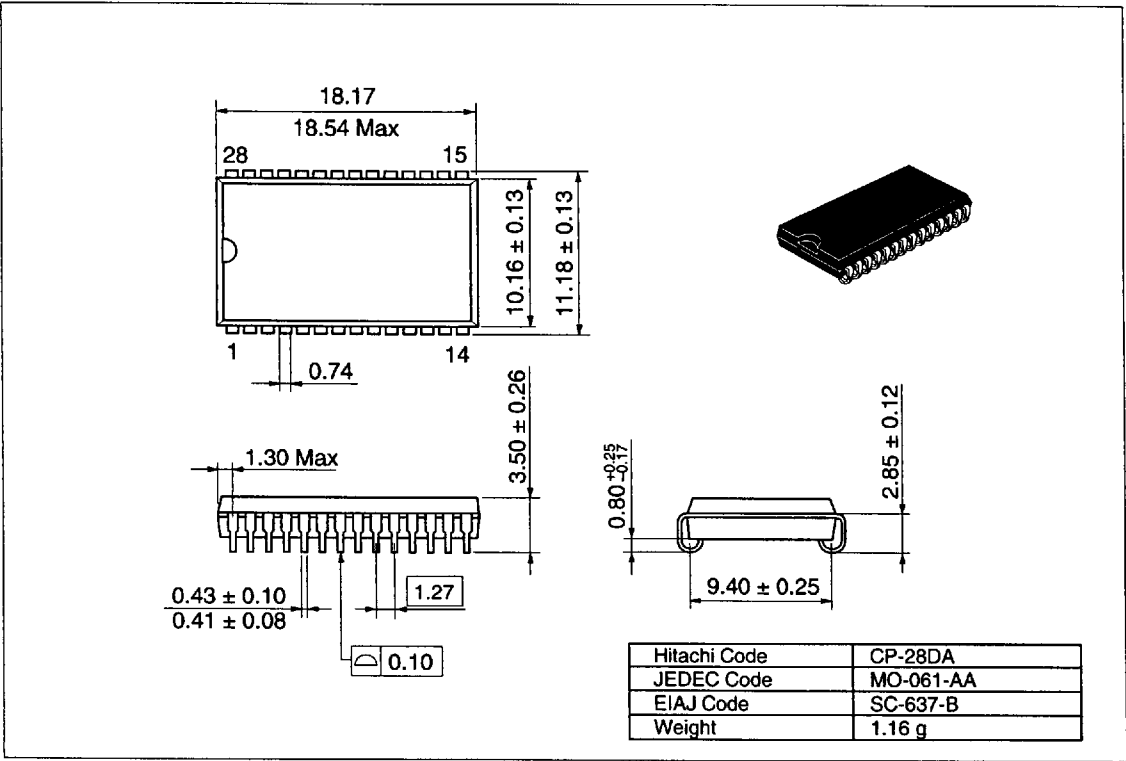
Self Refresh Cycle (L-version)*19, *20, *21, *22



HM51W17800 Series

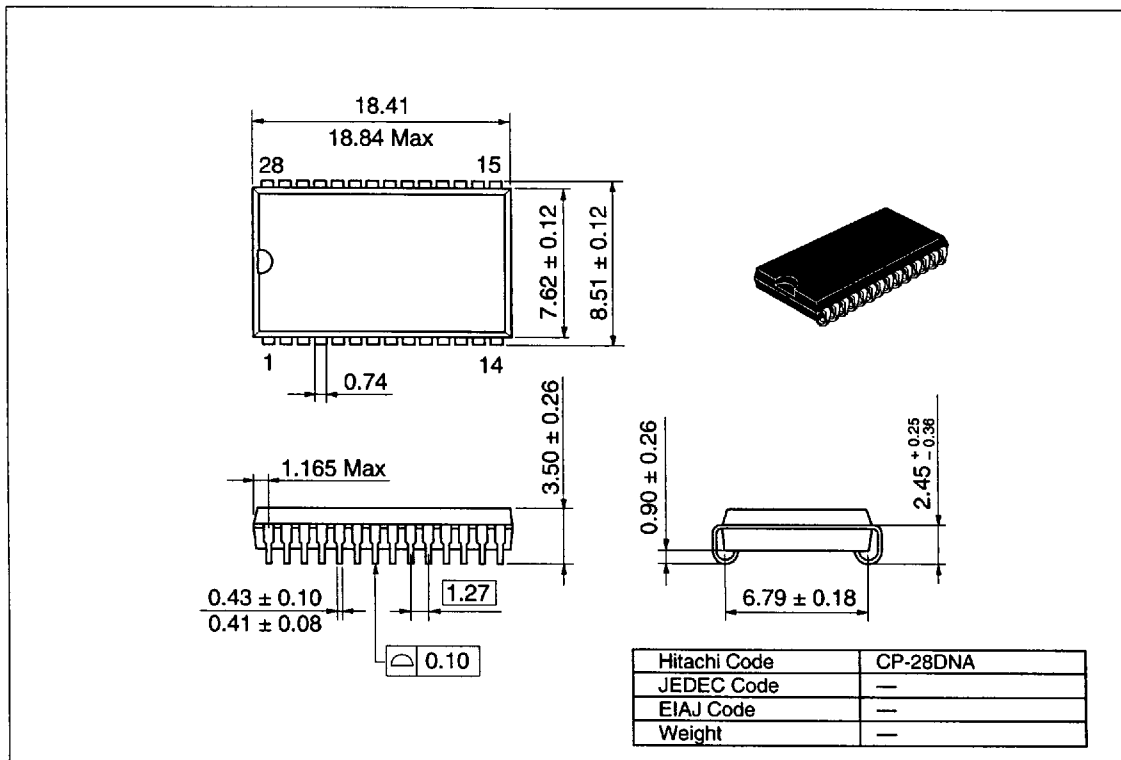
Package Dimensions

HM51W17800J/LJ Series (CP-28DA)



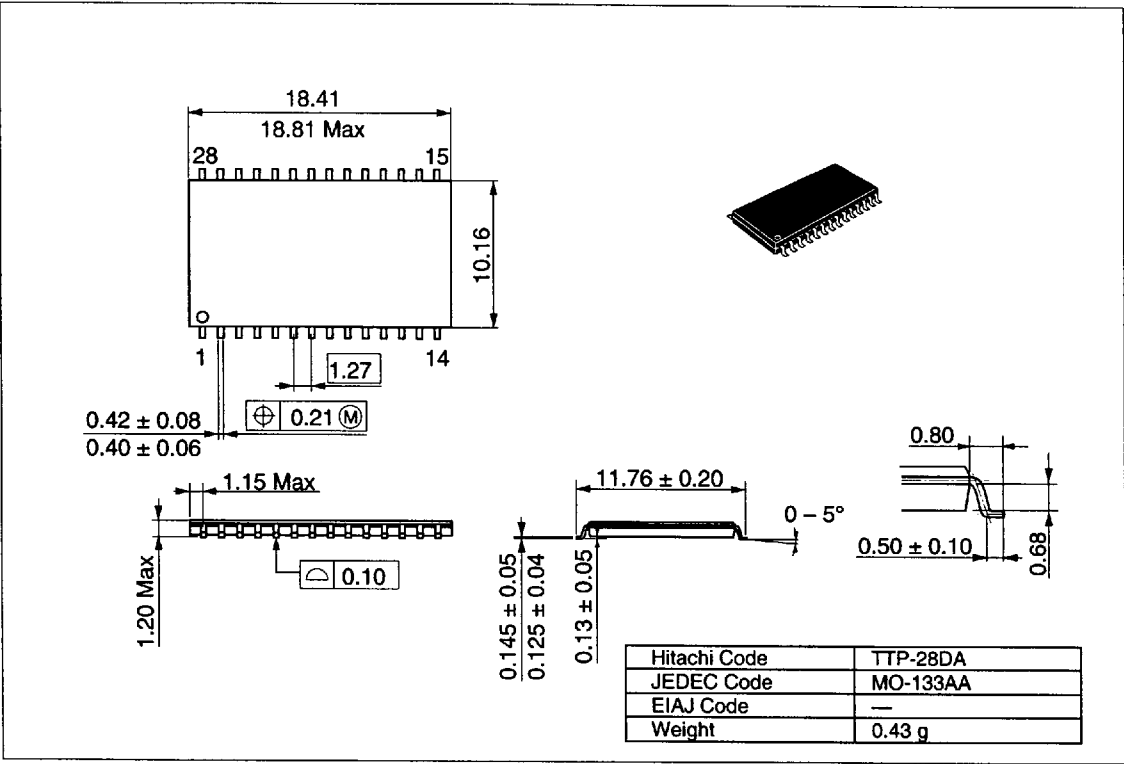
HM51W17800 Series

HM51W17800S/LS Series (CP-28DNA)



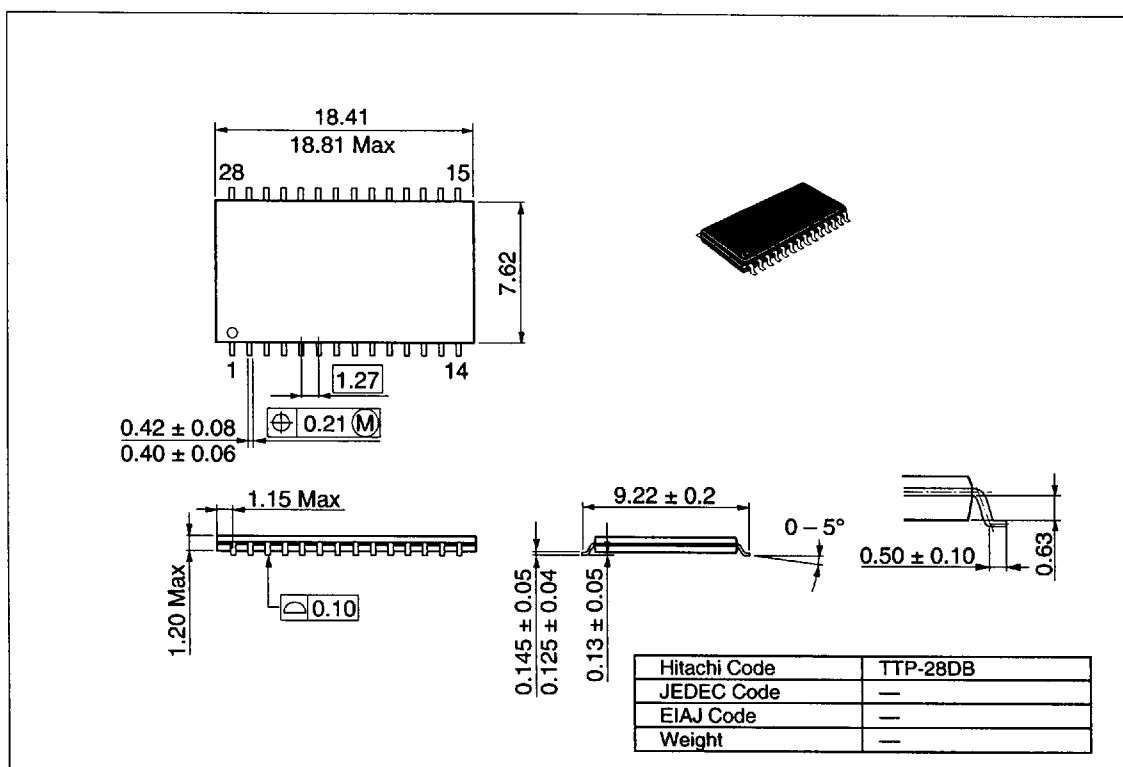
HM51W17800TT/LTT Series (TTP-28DA)

HM51W17800 Series



HM51W17800TS/LTS Series (TTP-28DB)

HM51W17800 Series



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Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
1.0	Sep. 30, 1996	Initial issue	Y. Kasama	M. Mishima
2.0	Dec. 5, 1996	Addition of HM51W17800-5 Series Addition of HM51W17800S/LS Series (CP-28DNA) Addition of HM51W17800TS/LTS Series (TTP-28DB) Power dissipation (active) 432/396 mW(max) to 396/360/324 mW (max) DC Characteristics I _{CC1} max: 120/110 mA to 110/100/90 mA I _{CC3} max: 120/110 mA to 110/100/90 mA I _{CC6} max: 120/110 mA to 110/100/90 mA I _{CC7} max: 100/90 mA to 100/90/85 mA AC Characteristics t _{RRH} min: 0/0 ns to 5/5/5 ns t _{RPC} min: 0/0 ns to 5/5/5 ns	Y. Kasama	M. Mishima
3.0	Feb. 24, 1997	AC Characteristics t _{RRH} min: 5/5/5 ns to 0/0/0 ns		